



Material Content Data Sheet



Sales Product Name		BSC060P03NS3E G		Issued		25. January 2018		
MA#		MA001404414						
Package		PG-TDSON-8-1		Weight*		120.94 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	2.479	2.05	2.05	20499	20499
leadframe	non noble metal	iron	7439-89-6	0.038	0.03		313	
	inorganic material	phosphorus	7723-14-0	0.011	0.01		94	
	non noble metal	copper	7440-50-8	37.762	31.20	31.24	312234	312641
wire	non noble metal	copper	7440-50-8	0.057	0.05	0.05	475	475
encapsulation	organic material	carbon black	1333-86-4	0.083	0.07		690	
	plastics	epoxy resin	-	5.923	4.90		48978	
	inorganic material	silicondioxide	60676-86-0	35.707	29.52	34.49	295246	344914
leadfinish	non noble metal	tin	7440-31-5	1.470	1.22	1.22	12153	12153
plating	noble metal	silver	7440-22-4	0.166	0.14	0.14	1369	1369
solder	noble metal	silver	7440-22-4	0.057	0.05		475	
	non noble metal	tin	7440-31-5	0.046	0.04		380	
	non noble metal	lead	7439-92-1	2.195	1.82	1.91	18151	19006
CLIP plating	noble metal	silver	7440-22-4	1.289	1.07	1.07	10662	10662
heatspreader	non noble metal	iron	7439-89-6	0.011	0.01		94	
	inorganic material	phosphorus	7723-14-0	0.003	0.00		28	
	non noble metal	copper	7440-50-8	11.320	9.36	9.37	93600	93722
heat sink CLIP	non noble metal	iron	7439-89-6	0.022	0.02		185	
	inorganic material	phosphorus	7723-14-0	0.007	0.01		55	
	non noble metal	copper	7440-50-8	22.292	18.43	18.46	184319	184559
*deviation	< 10%		Sum in total:			100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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